

PRESS RELEASE

LPKF and BASF close know-how and licence agreement

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Laser manufacturer LPKF AG and the plastic producer BASF AG signed a know-how and licence agreement covering the LDS method for the production of 3D electronic circuits (3D-MID). This agreement makes new materials (PA, POM, PES and PSU) available worldwide for the LPKF LDS method.

The high performance technical plastics made by BASF AG are already used for the production of electronic housings and components. The semi-aromatic PA Ultramid T in particular stands out for its high temperature resistance and is therefore ideal for soldering and withstanding extremely high thermal loads.

The LDS method developed by LPKF (Laser Direct Structuring) enables the electronics industry to create circuits directly on the surface of three dimensional plastic components. The LDS method involves the production of moulded components by conventional means using specially modified plastics. The surface is then activated by an LPKF laser along the precise tracks specified by the individual circuit layout. In the next step, copper conducting lines are deposited along these activated tracks in a chemical bath. Typical applications for this method are the antennae structures in mobile phones, sensors for security technology, or plastic components for the automotive industry.

The LDS technology developed by LPKF is an important mechatronic milestone – the integration of electronic components within functional mechanical parts. The combination of BASF materials and LPKF 3D laser systems is another breakthrough opening up new possibilities for 3D-MID applications.

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